

MF0 IC U1

Functional specification contactless single-trip ticket IC

Rev. 3.2 — 3 April 2007
028632

Product data sheet
PUBLIC

1. General description

NXP has developed the mifare MF0 IC U1 to be used with Proximity Coupling Devices (PCD) according to ISO/IEC14443A. The communication layer (mifare RF Interface) complies to parts 2 and 3 of the ISO/IEC14443A standard. The MF0 IC U1 is primarily designed for contactless single trip ticket solutions in transport applications.

1.1 Contactless energy and data transfer

In the mifare system, the MF0 IC U1 is connected to a coil with a few turns. The MF0 IC U1 fits for the TFC.0 (Edmonson) and TFC.1 ticket formats as defined in EN753-2.

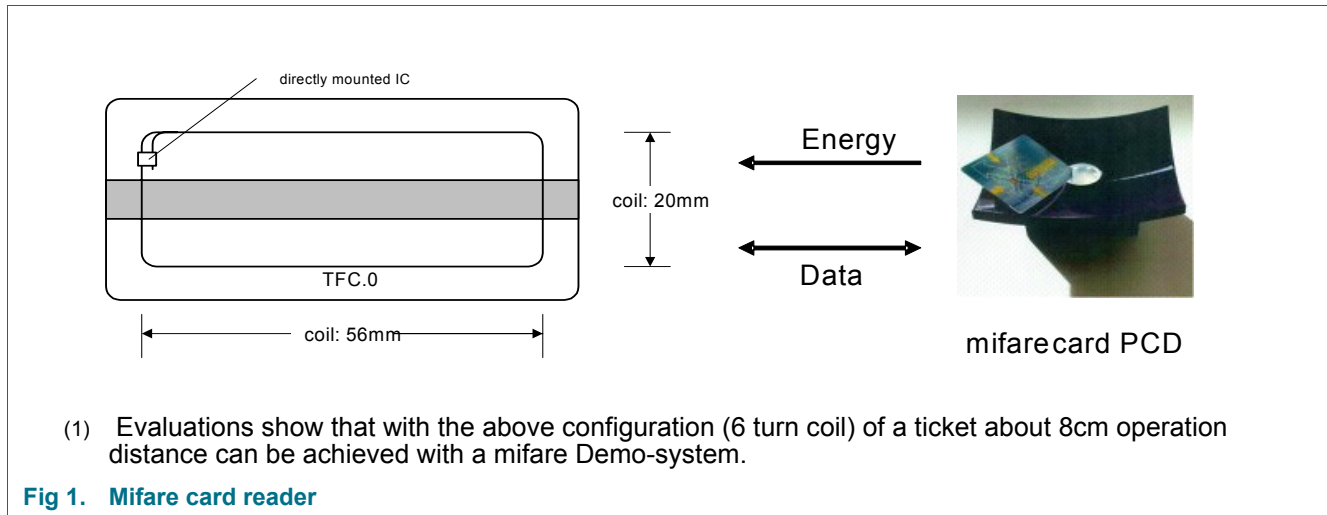
TFC.1 ticket formats are supported by the MF0 IC U10 chip featuring an on-chip resonance capacitor of 17 pF.

The smaller TFC.0 tickets are supported by the MF0 IC U11 chip holding an on-chip resonance capacitor of 50 pF.

No battery is needed. When the ticket is positioned in the proximity of the coupling device (PCD) antenna, the high speed RF communication interface allows to transmit data with 106 kBit/s.

1.2 Anticollision

An intelligent anticollision function allows to operate more than one card in the field simultaneously. The anticollision algorithm selects each card individually and ensures that the execution of a transaction with a selected card is performed correctly without data corruption resulting from other cards in the field.



1.2.1 Cascaded UID

The anticollision function is based on an IC individual serial number called Unique IDentification. The UID of the MF0 IC U1 is 7 bytes long and supports cascade level 2 according to ISO/IEC14443-3.

1.3 Security

The 7 byte UID is unchangeably programmed into each device during production. It cannot be altered and guarantees the uniqueness of each device. This is an effective anti-cloning mechanism. It may be used for a crypto-graphically secured data storage in the ticket memory. The UID may be used to derive diversified keys per ticket for an appropriate cryptographic system.

The 32 Bit OTP area provides write once operations e.g. for a one-time counter. It may be used for permanent de-validation of a ticket.

The field programmable read-only locking function allows to fix data per page to an unchangeable value. This function may be used to uniquely program the device for a dedicated application.

1.4 Delivery options

[MF0ICU1 can be delivered packaged or on wafer, please see delivery type description for more information.](#)

2. Features

2.1 Mifare, RF Interface (ISO/IEC 14443 A)

- Contactless transmission of data and supply energy (no battery needed)
- Operating distance: Up to 100mm (depending on antenna geometry)
- Operating frequency: 13.56 MHz
- Fast data transfer: 106 kbit/s
- High data integrity: 16 Bit CRC, parity, bit coding, bit counting

- True anticollision
- 7 byte serial number (cascade level 2 according to ISO/IEC14443-3)
- Typical ticketing transaction: < 35 ms
- Fast counter transaction: < 10 ms

2.2 EEPROM

- 512 bit, organised in 16 pages with 4 byte each
- Field programmable read-only locking function per page
- 32 bit user definable One Time Programmable (OTP) area
- 384 bit user r/w area (12 pages)
- Data retention of 5 years
- Write endurance 10000 cycles

2.3 Security

- Anti-cloning support by unique 7 Byte serial number for each device
- 32 Bit user programmable OTP area
- Field programmable read-only locking function per page

3. Ordering information

[See Delivery Type Addendum of Device](#)

4. Block diagram

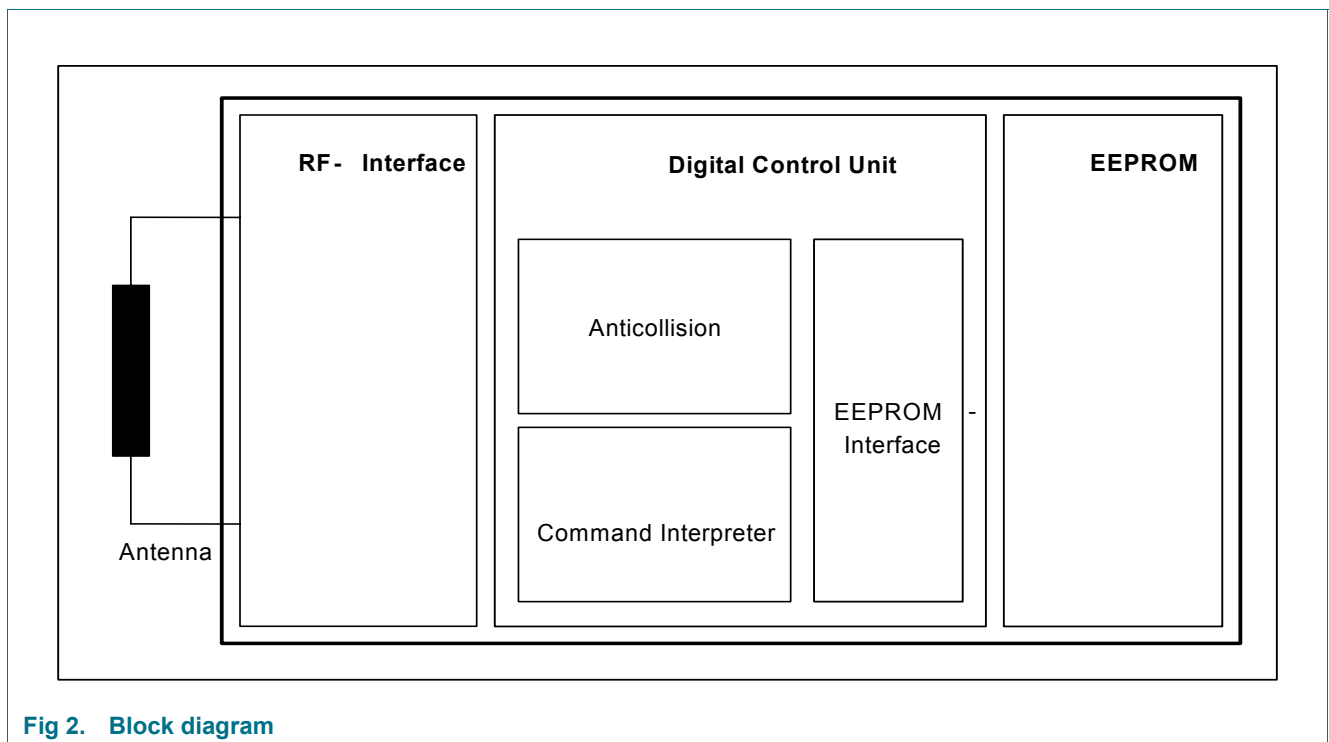


Fig 2. Block diagram

5. Pinning information

5.1 Pinning

[See Delivery Type Addendum of Device](#)

6. Functional description

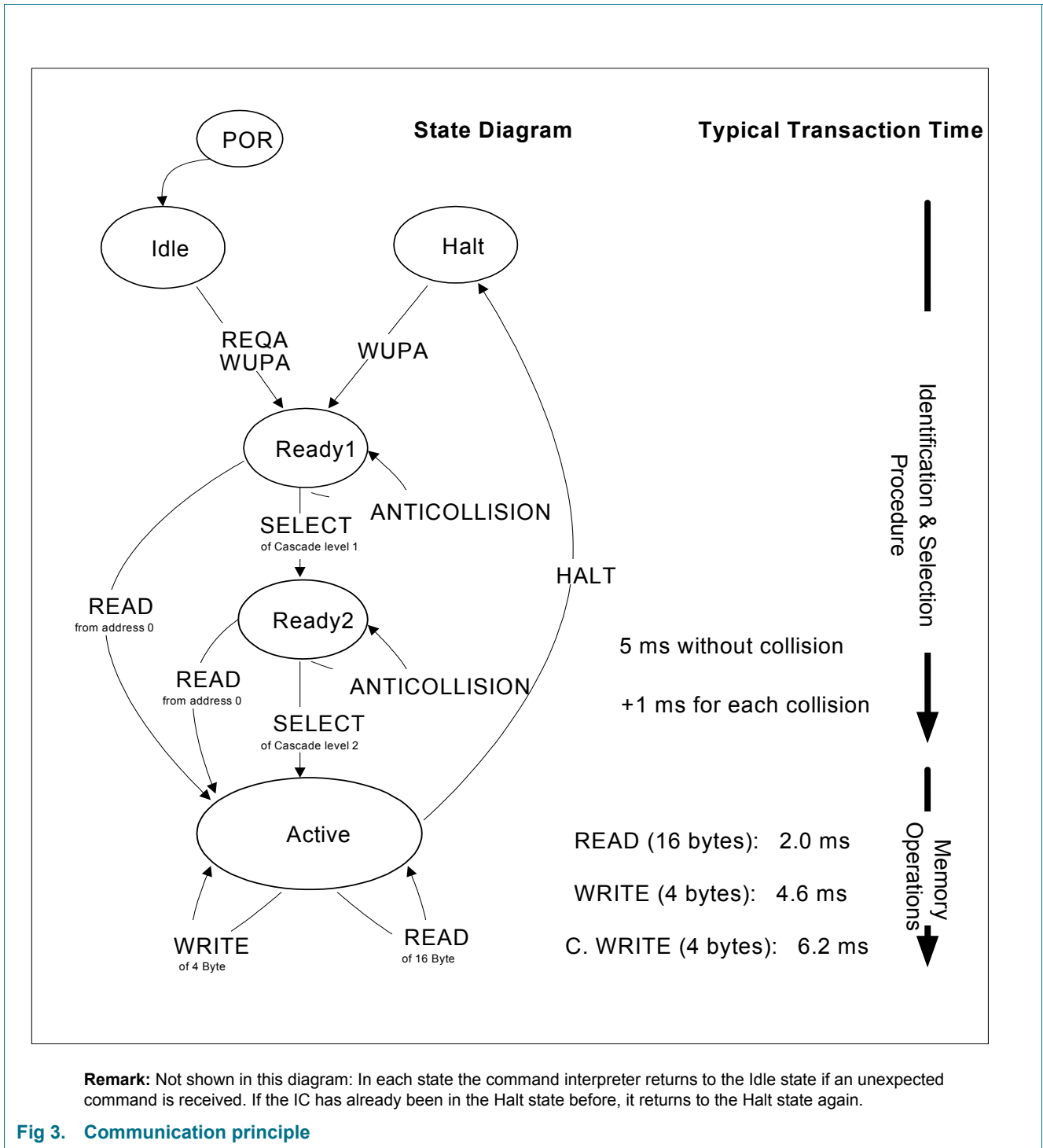
6.1 Block description

The MF0 IC U1 chip consists of the 512 bit EEPROM, the RF-Interface and the Digital Control Unit. Energy and data are transferred via an antenna, which consists of a coil with a few turns directly connected to the MF0 IC U1. No further external components are necessary. (For details on antenna design please refer to the document *mifare (Card) IC Coil Design Guide*.)

- RF-Interface:
 - Modulator/Demodulator
 - Rectifier
 - Clock Regenerator
 - Power On Reset
 - Voltage Regulator
- Anticollision: Several cards in the field may be selected and operated in sequence
- Command Interpreter: Handles the commands supported by the MF0 IC U1 in order to access the memory
- EEPROM-Interface
- EEPROM: 512 bits are organized in 0x16 pages with 4 bytes each. 80 bits are reserved for manufacturer data. 16 bits are used for the read-only locking mechanism. 32 bits are available as OTP area. 384 bits are user programmable read / write memory.

6.2 Communication principle

The commands are initiated by the PCD and controlled by the Command Interpreter of the MF0 IC U1. It handles the internal states and generates the appropriate responses.



6.2.1 Idle

After Power On Reset (POR) the MF0 IC U1 jumps directly into the Idle state. With a REQA or a WUPA command sent from the PCD it leaves this state. Any other data received in this state is interpreted as an error and the MF0 IC U1 remains waiting in the Idle state.

After a correctly executed HALT command, the Halt state becomes the waiting state, which can be left via a WUPA command.

6.2.2 Ready1

In this state the MF0 IC U1 supports the PCD in resolving the first part of its UID (3 bytes) with the ANTICOLLISION or a SELECT command of cascade level 1. This state is left correctly after one of two commands:

- With the SELECT command of cascade level 1 the PCD brings the MF0 IC U1 into state Ready2 where the second part of the UID has to be resolved.
- With the READ (from address 0) command the complete anticollision mechanism may be skipped and the MF0 IC U1 jumps directly into the Active state.

Remark: If more than one MF0 IC U1 is in the field of the PCD, a read from address 0 will cause a collision because of the different serial numbers, but all MF0 IC U1 devices will be selected! Any other data received in state Ready1 state is interpreted as an error and the MF0 IC U1 jumps back to its waiting state (IDLE or HALT, depending on it's previous state).

6.2.3 Ready2

In this state, which is similar to state Ready1, the MF0 IC U1 supports the PCD in resolving the second part of its UID (4 bytes) with the ANTICOLLISION command of cascade level 2. This state is usually left with the SELECT command of cascade level 2.

Alternatively, state Ready2 may be skipped via a READ (from address 0) command as described in state Ready1.

Remark: If more than one MF0 IC U1 is in the field of the PCD, a read from address 0 will cause a collision because of the different serial numbers, but all MF0 IC U1 devices will be selected! The response of the MF0 IC U1 to the SELECT of cascade level 2 command is the SAK (Select Acknowledge) byte. According to ISO/IEC14443 this byte indicates whether the anticollision cascade procedure is finished. In addition it defines for the MIFARE architecture platform the type of the selected device. Now the MF0 IC U1 is uniquely selected and only this device will continue communication with the PCD even if other contactless devices are in the field of the PCD. Any other data received in this state is interpreted as an error and the MF0 IC U1 jumps back to its waiting state (IDLE or HALT, depending on it's previous state).

6.2.4 Active

In the Active state either a READ (16 bytes) or a WRITE (4 bytes) command may be performed. The correct way to leave this state is to send a HALT command. Any other data received in this state is interpreted as an error and the MF0 IC U1 jumps back to its waiting state (IDLE or HALT, depending on it's previous state).

6.2.5 Halt

Besides the Idle state the Halt state constitutes the second waiting state implemented in the MF0 IC U1. A MF0 IC U1 that has already been processed can be set into this state via the HALT command. This state helps the PCD in the anticollision phase to distinguish between already processed cards and cards that have not been selected yet. The only way to get the MF0 IC U1 out of this state is the WUPA command. Any other data received in this state is interpreted as an error and the MF0 IC U1 remains in this state.

For a correct implementation of an anticollision procedure based on the usage of the Idle and Halt states and the REQA and WUPA commands please refer to the document mifare collection of currently available application Notes.

6.3 Date integrity

The following mechanisms are implemented in the contactless communication link between PCD and MF0 IC U1 to ensure a reliable data transmission:

- 16 bits CRC per block
- Parity bits for each byte
- Bit count checking
- Bit coding to distinguish between "1", "0", and no information
- Channel monitoring (protocol sequence and bit stream analysis)

6.4 RF interface

The RF-interface is according to the standard for contactless smart cards ISO/IEC 14443A.

The RF-field from the PCD is always present (with short pauses when transmitting), because it is used for the power supply of the card.

For both directions of data communication there is only one start bit at the beginning of each frame. Each byte is transmitted with a parity bit (odd parity) at the end. The LSB of the byte with the lowest address of the selected block is transmitted first. The maximum frame length is 163 bits (16 data bytes + 2 CRC bytes = $16 * 9 + 2 * 9 + 1$ start bit).

6.5 Memory organization

The 512 bit EEPROM memory is organised in 0x16 pages with 4 bytes each. In the erased state the EEPROM cells are read as a logical "0", in the written state as a logical "1".

Byte Number	0x00	0x01	0x02	0x03	Page
Serial Number	SN0	SN1	SN2	BCC0	0x00
Serial Number	SN3	SN4	SN5	SN6	0x01
Internal / Lock	BCC1	Internal	Lock0	Lock1	0x02
OTP	OTP0	OTP1	OTP2	OTP3	0x03
Data Read/Write	Data0	Data1	Data2	Data3	0x04
Data Read/Write	Data4	Data5	Data6	Data7	0x05
Data Read/Write	Data8	Data9	Data10	Data11	0x06
Data Read/Write	Data12	Data13	Data14	Data15	0x07
Data Read/Write	Data16	Data17	Data18	Data19	0x08
Data Read/Write	Data20	Data21	Data22	Data23	0x09
Data Read/Write	Data24	Data25	Data26	Data27	0x0A
Data Read/Write	Data28	Data29	Data30	Data31	0x0B
Data Read/Write	Data32	Data33	Data34	Data35	0x0C
Data Read/Write	Data36	Data37	Data38	Data39	0x0D
Data Read/Write	Data40	Data41	Data42	Data43	0x0E
Data Read/Write	Data44	Data45	Data46	Data47	0x0F

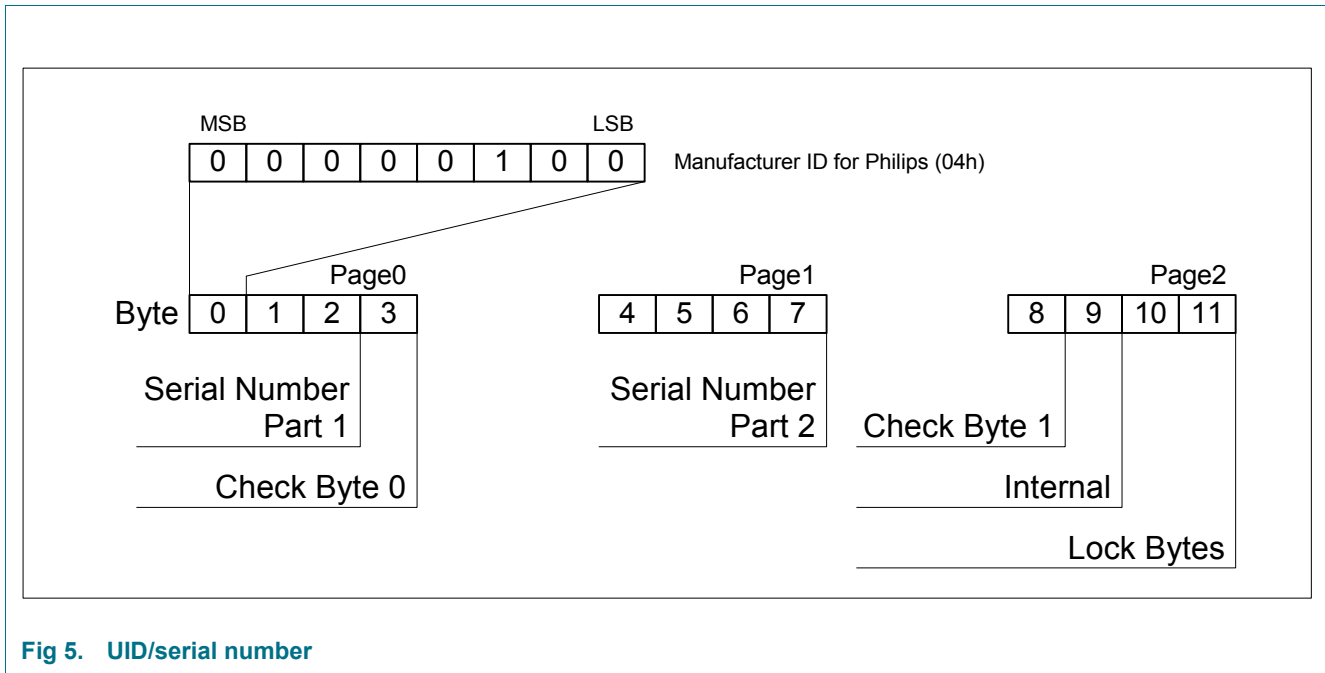
MF0 U1
memory
map

Remark: Bold frame indicates user area

Fig 4. Memory organization

6.5.1 UID/serial number

The unique 7 byte serial number (UID) and its two Check Bytes are programmed into the first 9 bytes of the memory. It therefore covers page 0x00, page 0x01 and the first byte of page 0x02. The second byte of page 0x02 is reserved for internal data. Due to security and system requirements these bytes are write-protected after having been programmed by the IC manufacturer after production.



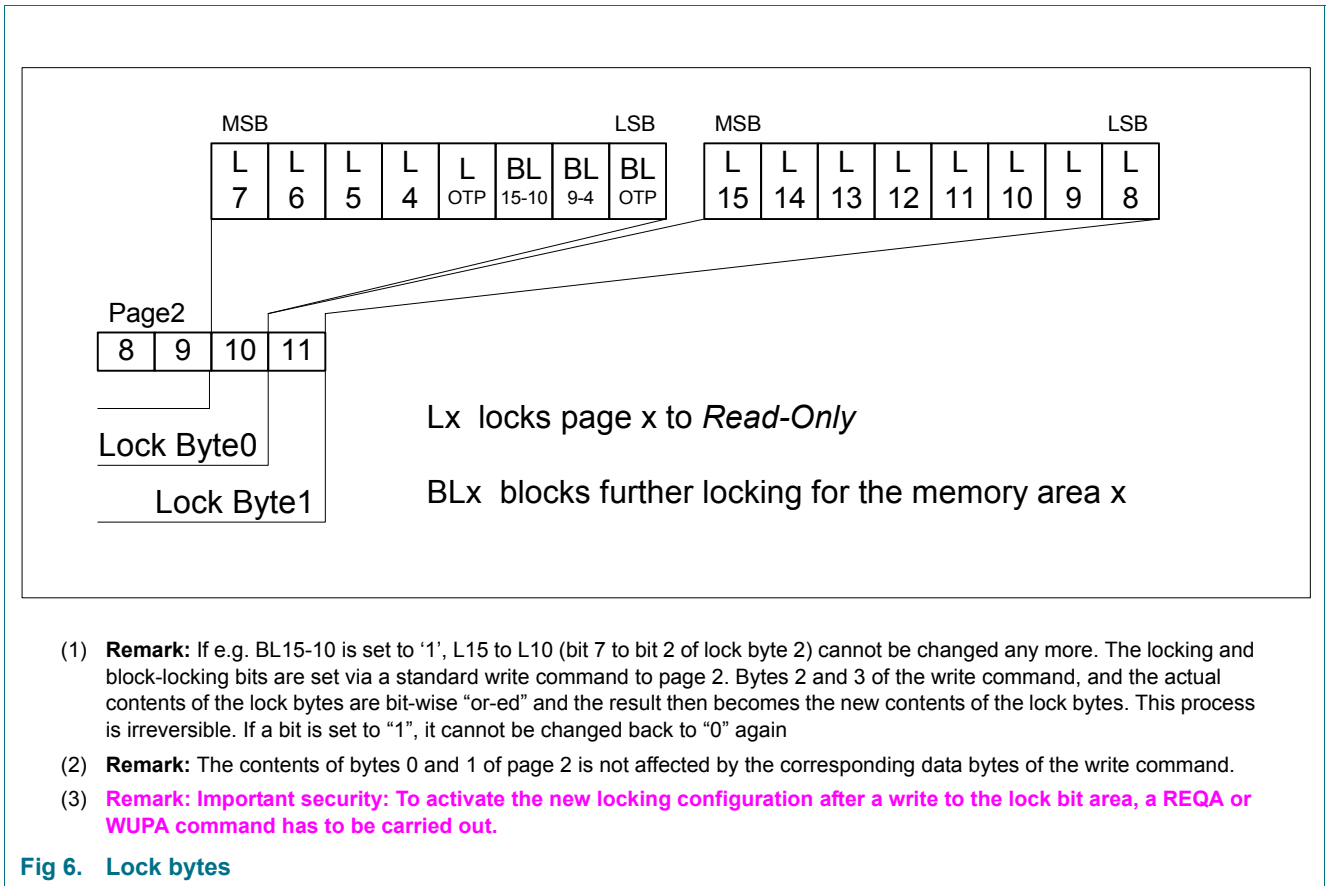
According to ISO/IEC14443-3 Check Byte0 (BCC0) is defined as $CT \oplus SN0 \oplus SN1 \oplus SN2$ and Check Byte 1 (BCC1) is defined as $SN3 \oplus SN4 \oplus SN5 \oplus SN6$.

SN0 holds the Manufacturer ID for NXP (0x04) according to ISO/IEC14443-3 and ISO/IEC.7816-6 AMD.1.

6.5.2 Lock bytes

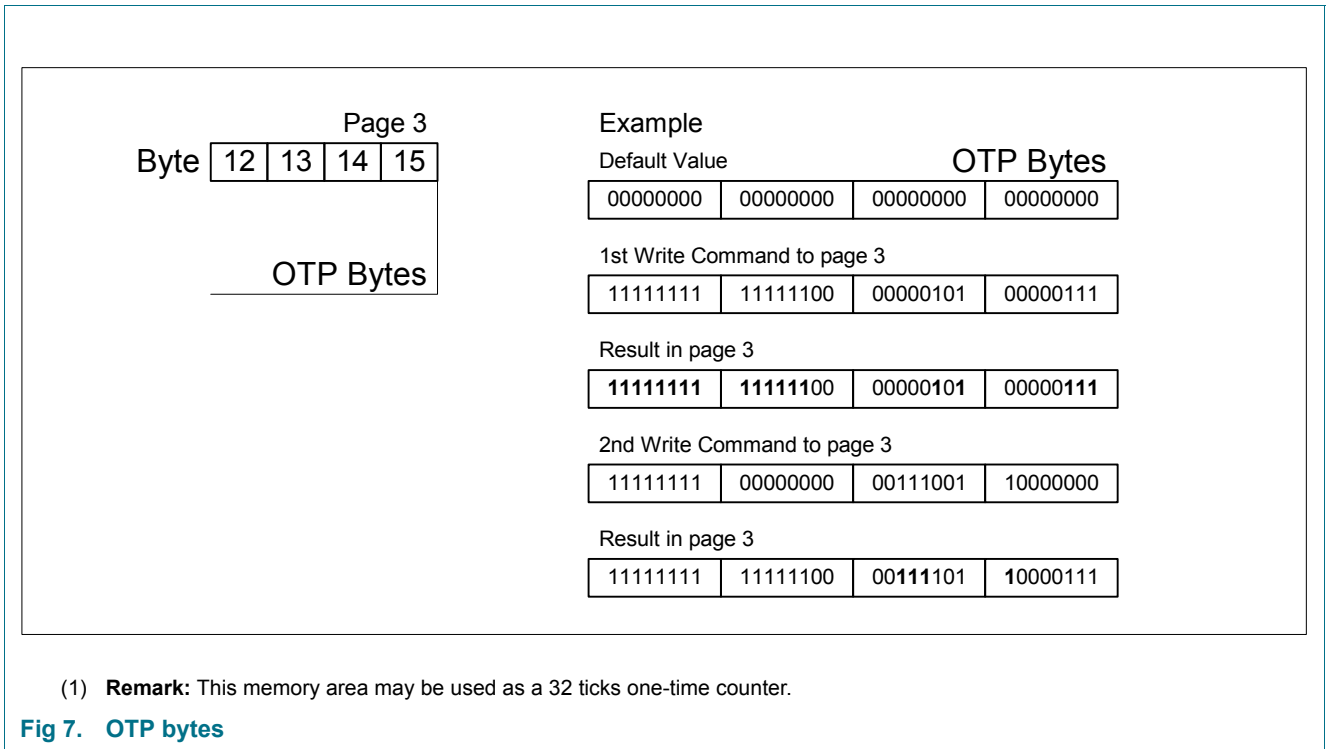
The bits of Byte 0x02 and 0x03 of page 0x02 represent the field-programmable read-only locking mechanism. Each page x from 0x03 (OTP) to 0x0E may be locked individually to prevent further write access by setting the corresponding locking bit Lx to 1. After locking the page is read-only memory.

The 3 least significant bits of lock byte 0 are the block-locking bits. Bit 2 handles pages 0x0E to 0x10, bit 0x01 pages 0x09 to 0x04 and bit 0x00 page 0x03 (OTP). Once the block-locking bits are set the locking configuration for the corresponding memory area is frozen.



6.5.3 OTP bytes

Page 0x03 is the OTP page. It is pre-set to all "0" after production. These bytes may be bit-wise modified by a write command.



The bytes of the write command and the current contents of the OTP bytes are bit-wise “or-ed” and the result becomes the new contents of the OTP bytes. This process is irreversible. If a bit is set to “1”, it cannot be changed back to “0” again.

6.5.4 Data pages

Pages 0x04 to 0x15 constitute the user read/write area. After production the data pages are initialised to all "0".

6.6 Command set

The MF0 IC U1 comprises the following command set:

6.6.1 REQA

Table 1. REQA

Code	Parameter	Data	Integrity mechanism	Response
0x26 (7 Bit)	-	-	Parity	0x0044

Description: The MF0 IC U1 accepts the REQA command in Idle state only. The response is the 2-byte ATQA (0x0044). REQA and ATQA are implemented fully according to ISO/IEC14443-3.

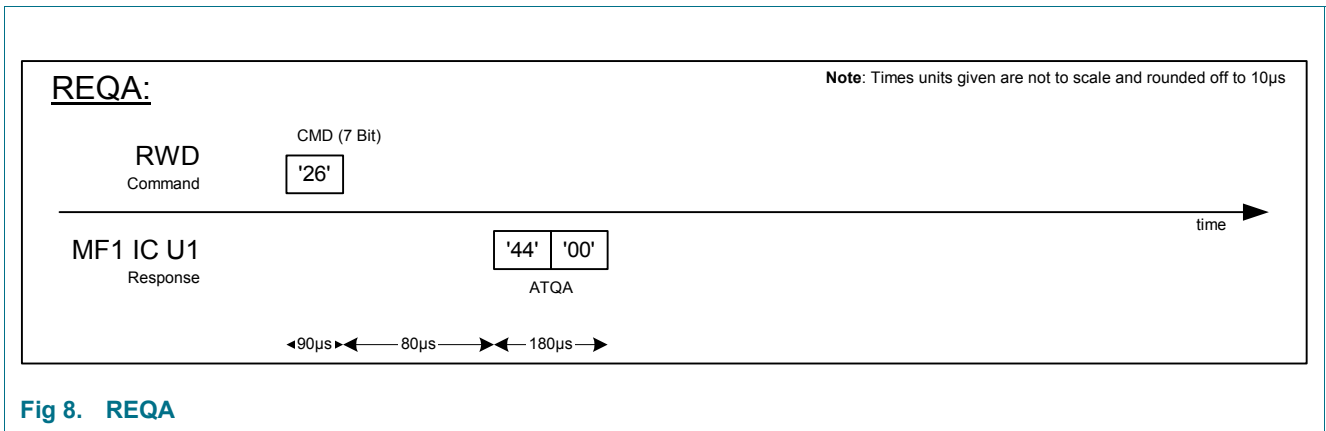


Fig 8. REQA

6.6.2 WUPA

Table 2. WUPA

Code	Parameter	Data	Integrity mechanism	Response
0x52 (7Bit)	-	-	Parity	0x0044

Description: The MF0 IC U1 accepts the WUPA command in the Idle and Halt state only. The response is the 2-byte ATQA (0x0044). WUPA is implemented fully according to ISO/IEC14443-3.

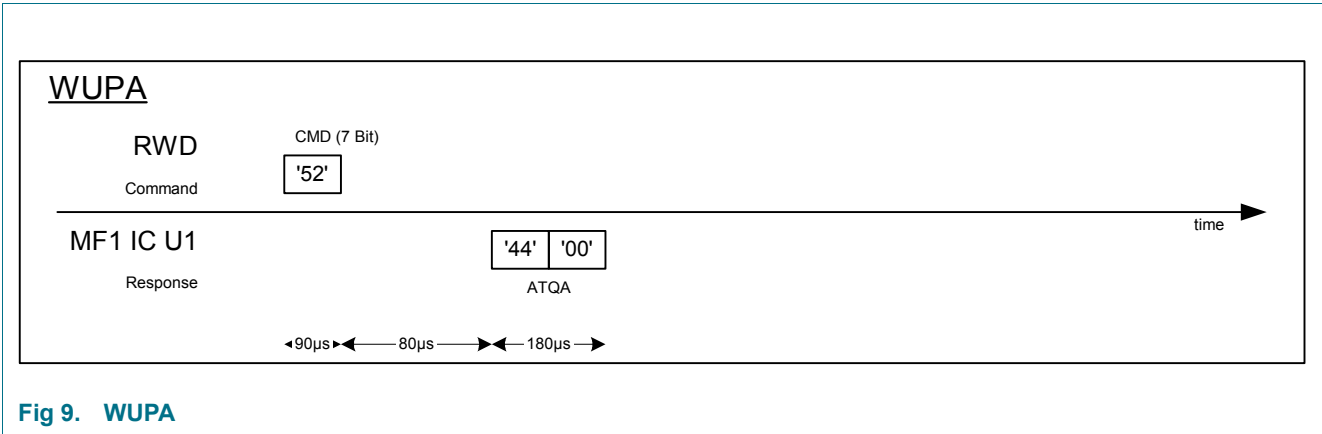


Fig 9. WUPA

6.6.3 ANTICOLLISION and SELECT of cascade level 1

Table 3. ANTICOLLISION and SELECT of cascade level 1

Code	Parameter	Data	Integrity mechanism	Response
Anticollision: 0x93	0x20 – 0x67	Part of the UID	Parity	Parts of UID
Select: 0x93	0x70	First 3 bytes of UID	Parity, BCC, CRC	SAK ('04')

Description: The ANTICOLLISION and SELECT commands are based on the same command code. They differ only in the Parameter byte. This byte is per definition 0x70 in case of SELECT. The MF0 IC U1 accepts these commands in the Ready1 state only. The response is part 1 of the UID.

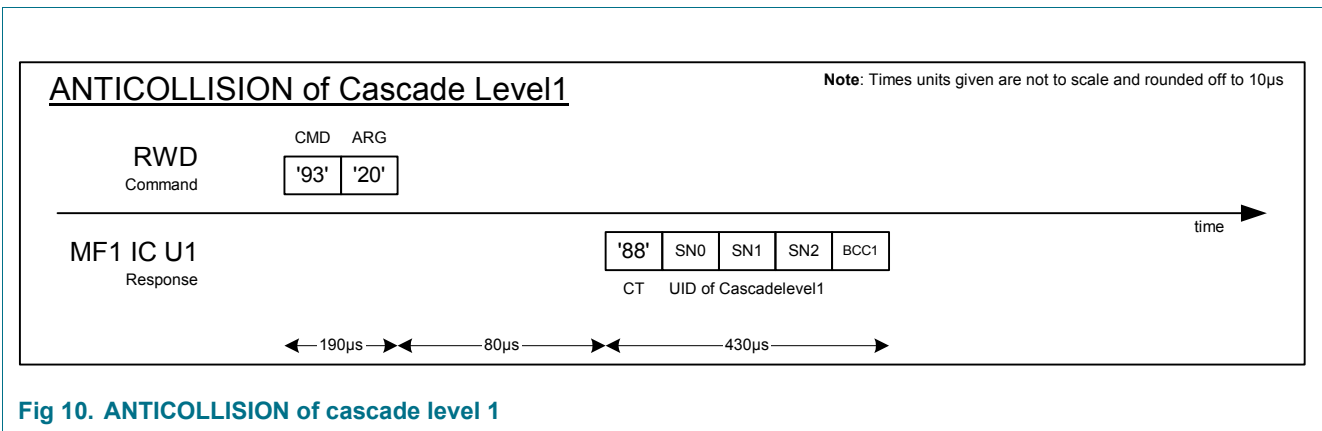


Fig 10. ANTICOLLISION of cascade level 1

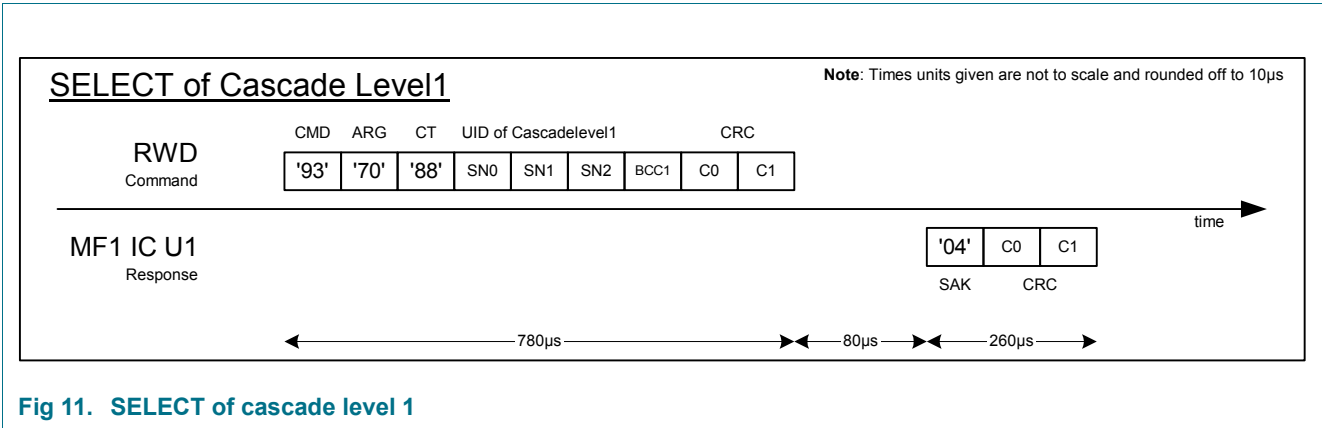


Fig 11. SELECT of cascade level 1

6.6.4 ANTICOLLISION and SELECT of cascade level 2

Table 4. ANTICOLLISION and SELECT of cascade level 2

Code	Parameter	Data	Integrity mechanism	Response
Anticollision: 0x95	0x20 – 0x67	Part of the UID	Parity	Parts of UID
Select: 0x95	0x70	Second 4 bytes of UID	Parity, BCC, CRC	SAK ('00')

Description: The ANTICOLLISION and SELECT command are based on the same command code. They differ only in the parameter byte. This byte is per definition 0x70 in case of SELECT. The MF0 IC U1 accepts these commands in the Ready2 state only. The response is part 2 of the UID.

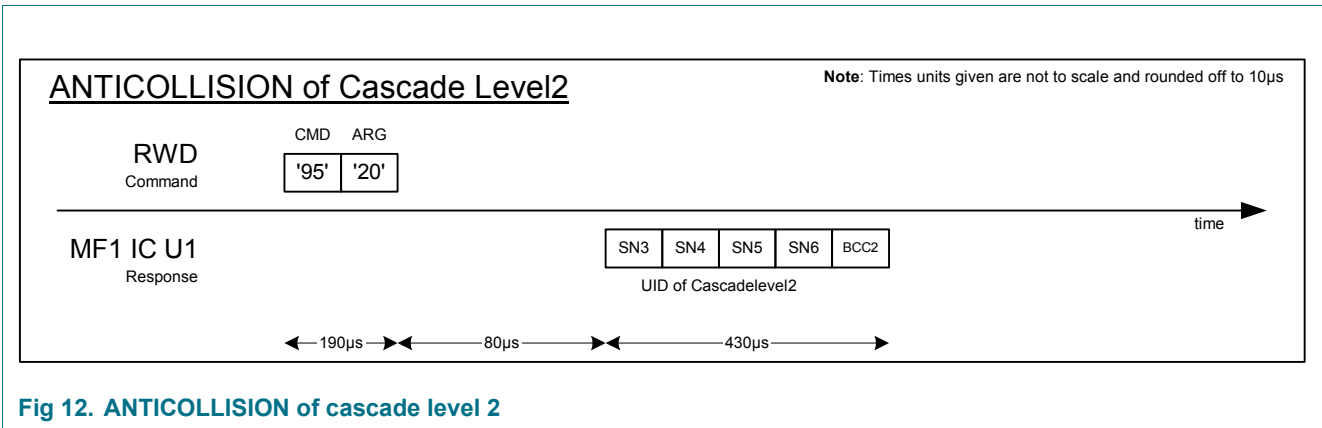


Fig 12. ANTICOLLISION of cascade level 2

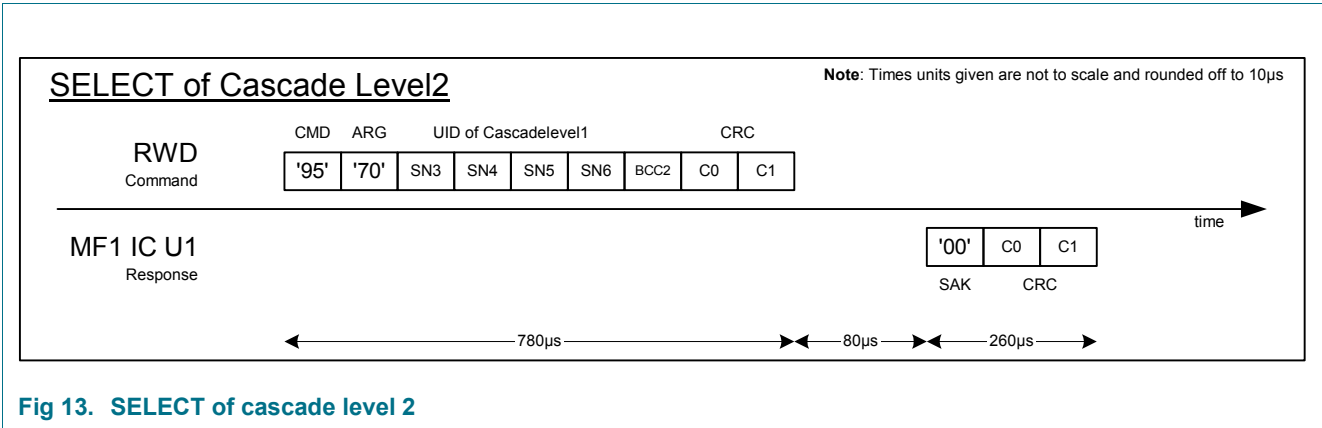


Fig 13. SELECT of cascade level 2

6.6.5 Read

Table 5. Read

Code	Parameter	Data	Integrity mechanism	Response
0x30	ADR: 0X00-0X0F	-	CRC	16 Byte Data

Description: The READ command needs the page address as a parameter. Only addresses 0x00 to 0x0F are decoded. For higher addresses the MF0 IC U1 returns a NAK. The MF0 IC U1 responds to the READ command by sending 16 bytes starting from the page address defined in the command (e.g. if ADR is '0x03' pages 0x03, 0x04, 0x05, 0x06 are returned). A roll back is implemented; e.g. if ADR is '0X0E', the contents of pages 0X0E, 0X0F, 0x00 and 0x01 is returned).

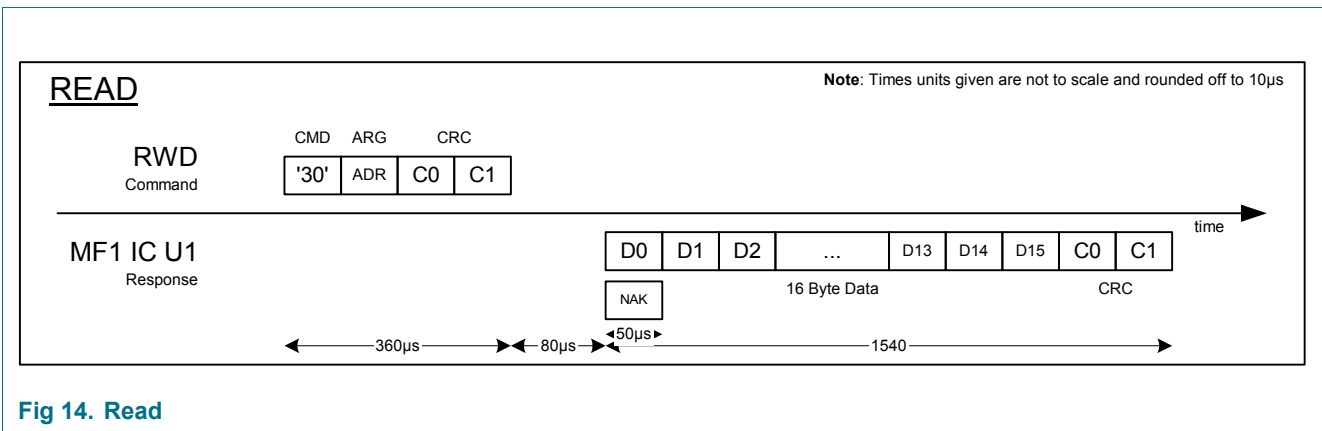


Fig 14. Read

6.6.6 Halt

Table 6. Halt

Code	Parameter	Data	Integrity mechanism	Response
0x50	0x00	-	Parity, CRC	Passive AK, NAK

Description: The HALT command is used to set already processed MF0 IC U1 devices into a different waiting state (Halt instead of Idle), which allows a simple separation between devices whose UIDs are already known (as they have already passed the anticollision procedure) and devices that have not yet been identified by their UIDs. This mechanism is a very efficient way of finding all contactless devices in the field of a PCD.

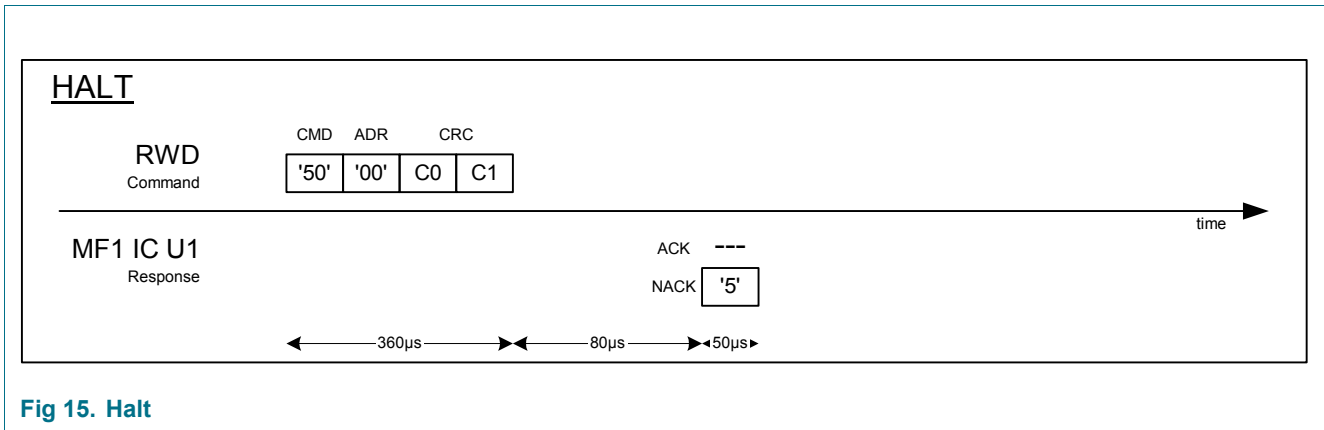


Fig 15. Halt

6.6.7 Write

Table 7. Write

Code	Parameter	Data	Code	Parameter
0xA2	ADR: 0X00-0X0F	4 Byte	0xA2	ADR: '0' – '7'

Description: The WRITE command is used to program the lock bytes in page 0x02, the OTP bytes in page 0x03 or the data bytes in pages 0X 04 to 0X0F. A WRITE command is performed page-wise, programming 4 bytes in a row.

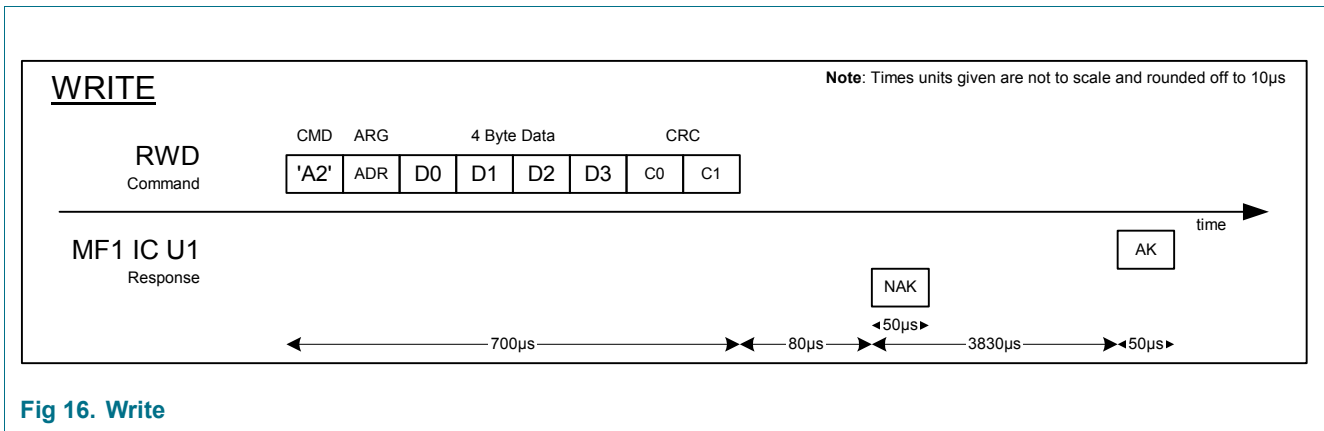


Fig 16. Write

6.6.8 Compatibility write

Table 8. Compatibility write

Cod e	Parameter	Data	Integrity mechanism	Response
0xA0	ADR: 0X00-0X0F	16 Byte	Parity, CRC	AK or NAK

Description: The COMPATIBILITY WRITE command was implemented to accommodate the established mifare PCD infrastructure. Even though 16 bytes are transferred to the MF0 IC U1, only the least significant 4 bytes (bytes 0 to 3) will be written to the specified address. It is recommended to set the remaining bytes 0X04 to 0X0F to all '0'.

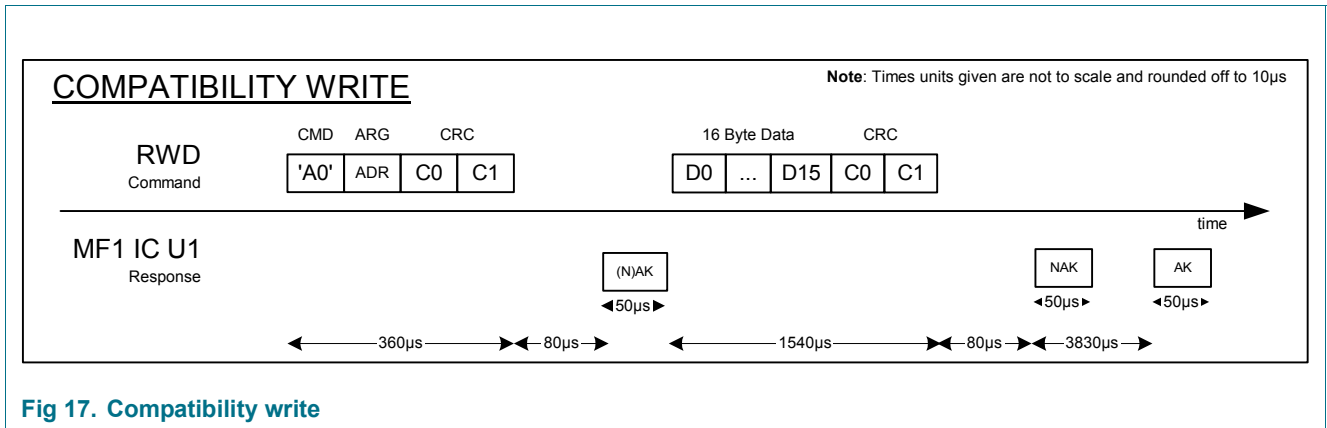


Fig 17. Compatibility write

6.7 Summary of relevant data for device identification

Table 9. Summary of relevant data for device identification

Code	Type	Value	Binary Format	Remark
ATQA	2 Byte	0x0044	0000 0000 0100 0100 1 st '1' indicates cascade level 2 2 nd '1' indicates MIFARE family	Hard Coded
CT	1 Byte Cascade Tag	0x88	1000 1000 ensures collision with cascade level 1 products	Hard Coded
SAK (casc. level 1)	1 Byte	0x04	0000 0100 '1' indicates additional cascade level	Hard Coded
SAK (casc. level 2)	1 Byte	0x00	0000 0000 indicates complete UID and MF0 IC U1 functionality	Hard Coded
Manufacturer Byte	1 Byte	0x04	0000 0100 indicates manufacturer NXP	Acc. to ISO/IEC 14443-3 and ISO/IEC 7816-6 AMD.1

7. Limiting values

[See Delivery Type Addendum of Device](#)

8. Recommended operating conditions

[See Delivery Type Addendum of Device](#)

9. Characteristics

[See Delivery Type Addendum of Device](#)

10. Support information

For additional information, please visit: <http://www.nxp.com>

11. Package outline

[See Delivery Type Addendum of Device](#)

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersede s
028610			First official version	1.0
028620			Introduction of Lock bytes and increase of memory to 512 bit. Correction of Manufacturer Code	2.0
028621	January 2003		Introduction of read in state Ready2 and Compatibility write command	2.1
028622	January 2003		Updated document layout + wording Change of Write endurance to 1000 cycles	2.2
028623	January 2003		Include MF0 IC U11 type	2.3
028624	February 2003	Preliminary Version		2.4
028625	March 2003		Write Endurance, Data Retention	2.5
028630	March 2003	Product data sheet		3.0
028631	March 2007	Product data sheet		3.1
028632	3 April 2007	Product data sheet	exchange of figure 11 and 13	3.2
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name. 			

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

13.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

13.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of a NXP Semiconductors product can reasonably be expected to

result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

13.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

Mifare — is a trademark of NXP B.V.

14. Contact information

For additional information, please visit: <http://www.nxp.com>

For sales office addresses, send an email to: salesaddresses@nxp.com

15. Tables

Table 1. REQA	13	Table 6. Halt	16
Table 2. WUPA	13	Table 7. Write	17
Table 3. ANTICOLLISION and SELECT of cascade level 1 14		Table 8. Compatibility write	17
Table 4. ANTICOLLISION and SELECT of cascade level 2 15		Table 9. Summary of relevant data for device identification 18	
Table 5. Read	16	Table 10. Revision history	20

16. Figures

Fig 1. Mifare card reader	2	Fig 10. ANTICOLLISION of cascade level 1	14
Fig 2. Block diagram	3	Fig 11. SELECT of cascade level 1	15
Fig 3. Communication principle	6	Fig 12. ANTICOLLISION of cascade level 2	15
Fig 4. Memory organization	9	Fig 13. SELECT of cascade level 2	16
Fig 5. UID/serial number	10	Fig 14. Read	16
Fig 6. Lock bytes	11	Fig 15. Halt	17
Fig 7. OTP bytes	12	Fig 16. Write	17
Fig 8. REQA	13	Fig 17. Compatibility write	18
Fig 9. WUPA	14		

17. Contents

1	General description	1	6.4	RF interface	8
1.1	Contactless energy and data transfer	1	6.5	Memory organization	8
1.2	Anticollision	1	6.5.1	UID/serial number	10
1.2.1	Cascaded UID	2	6.5.2	Lock bytes	10
1.3	Security	2	6.5.3	OTP bytes	11
1.4	Delivery options	2	6.5.4	Data pages	13
2	Features	2	6.6	Command set	13
2.1	Mifare, RF Interface (ISO/IEC 14443 A)	2	6.6.1	REQA	13
2.2	EEPROM	3	6.6.2	WUPA	13
2.3	Security	3	6.6.3	ANTICOLLISION and SELECT of cascade level 1 14	
3	Ordering information	3	6.6.4	ANTICOLLISION and SELECT of cascade level 2 15	
4	Block diagram	3	6.6.5	Read	16
5	Pinning information	4	6.6.6	Halt	16
5.1	Pinning	4	6.6.7	Write	17
6	Functional description	5	6.6.8	Compatibility write	17
6.1	Block description	5	6.7	Summary of relevant data for device identification 18	
6.2	Communication principle	5	7	Limiting values	18
6.2.1	Idle	6	8	Recommended operating conditions	18
6.2.2	Ready1	7	9	Characteristics	19
6.2.3	Ready2	7	10	Support information	19
6.2.4	Active	7			
6.2.5	Halt	7			
6.3	Date integrity	8			

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.



11 Package outline 19

12 Revision history 20

13 Legal information 21

13.1 Data sheet status 21

13.2 Definitions 21

13.3 Disclaimers 21

13.4 Trademarks 21

14 Contact information 21

15 Tables 22

16 Figures 22

17 Contents 22

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.



© NXP B.V. 2007.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 3 April 2007

Document identifier: 028632